



STB70NFS03L

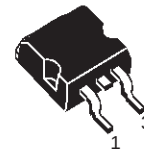
N-CHANNEL 30V - 0.008 Ω - 70A D²PAK STripFET™ MOSFET PLUS SCHOTTKY RECTIFIER

PRELIMINARY DATA

MAIN PRODUCT CHARACTERISTICS			
MOSFET	V _{DSS}	R _{DS(on)}	I _D
	30 V	<0.01 Ω	70 A
SCOTTKY	I _{F(AV)}	V _{RRM}	V _{F(MAX)}
	3 A	30 V	0.51 V

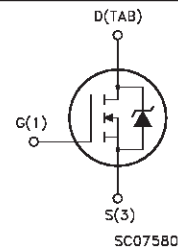
DESCRIPTION

This product associates a Power MOSFET of the third generation of STMicroelectronics unique "Single Feature Size" strip-based process and a low drop Schottky diode. The transistor shows the best trade-off between on-resistance and gate charge. Used as low side in buck regulators, the product is the best solution in terms of conduction losses and space saving.



**D²PAK
TO-263**
(suffix "T4")

INTERNAL SCHEMATIC DIAGRAM



MOSFET ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage (V _{GS} = 0)	30	V
V _{DGR}	Drain-gate Voltage (R _{GS} = 20 k Ω)	30	V
V _{GS}	Gate- source Voltage	± 22	V
I _D	Drain Current (continuous) at T _C = 25°C	70	A
I _D	Drain Current (continuous) at T _C = 100°C	50	A
I _{DM} (•)	Drain Current (pulsed)	280	A
P _{tot}	Total Dissipation at T _C = 25°C	100	W
	Derating Factor	0.67	W/°C
T _{stg}	Storage Temperature	-65 to 175	°C
T _j	Max. Operating Junction Temperature	175	°C

(•)Pulse width limited by safe operating area

SCHOTTKY ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V _{RRM}	Repetitive Peak Reverse Voltage		30	V
I _{F(RMS)}	RMS Forward Current		20	A
I _{F(AV)}	Average Forward Current	T _L =125 °C d=0.5	3	A
I _{FSM}	Surge Non Repetitive Forward Current	tp=10ms Sinusoidal	75	A
dv/dt	Critical Rate of Rise of Reverse Voltage		10000	V/ μ s

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THERMAL DATA

$R_{thj-case}$	Thermal Resistance Junction-case Max	Max	1.5	°C/W
$R_{thj-amb}$	Thermal Resistance Junction-ambient Max	Max	62.5	°C/W
T_j	Maximum Lead Temperature For Soldering Purpose		175	°C

ELECTRICAL CHARACTERISTICS ($T_{case} = 25\text{ °C}$ unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source Breakdown Voltage	$I_D = 250\text{ }\mu\text{A}$ $V_{GS} = 0$	30			V
I_{DSS}	Zero Gate Voltage Drain Current ($V_{GS} = 0$)	$V_{DS} = \text{Max Rating}$ $V_{DS} = \text{Max Rating}, T_C = 125\text{ °C}$			1 10	μA μA
I_{GSS}	Gate-body Leakage Current ($V_{DS} = 0$)	$V_{GS} = \pm 20\text{ V}$			± 100	nA

ON (*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ $I_D = 250\text{ }\mu\text{A}$	1			V
$R_{DS(on)}$	Static Drain-source On Resistance	$V_{GS} = 10\text{ V}$ $I_D = 35\text{ A}$ $V_{GS} = 5\text{ V}$ $I_D = 18\text{ A}$		0.008 0.015	0.01 0.018	Ω Ω
$I_{D(on)}$	On State Drain Current	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $V_{GS} = 10\text{ V}$	70			A

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$g_{fs}^{(*)}$	Forward Transconductance	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $I_D = 35\text{ A}$		40		S
C_{iss} C_{oss} C_{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitances	$V_{DS} = 25\text{ V}$ $f = 1\text{ MHz}$ $V_{GS} = 0$		1470 490 110		pF pF pF

ELECTRICAL CHARACTERISTICS (continued)**SWITCHING ON**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r	Turn-on Delay Time Rise Time	$V_{DD} = 15\text{ V}$ $I_D = 35\text{ A}$ $R_G = 4.7\ \Omega$ $V_{GS} = 10\text{ V}$ (see test circuit, Figure 3)		20 350		ns ns
Q_g Q_{gs} Q_{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 24\text{ V}$ $I_D = 46\text{ A}$ $V_{GS} = 10\text{ V}$		35 5 10	45	nC nC nC

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(off)}$ t_f	Turn-off Delay Time Fall Time	$V_{DD} = 24\text{ V}$ $I_D = 35\text{ A}$ $R_G = 4.7\ \Omega$ $V_{GS} = 10\text{ V}$ (Resistive Load, see fig.3)		35 65		ns ns

SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD} $I_{SDM}(\bullet)$	Source-drain Current Source-drain Current (pulsed)				70 280	A A
$V_{SD} (*)$	Forward On Voltage	$I_{SD} = 70\text{ A}$ $V_{GS} = 0$			1.5	V
t_{rr} Q_{rr} I_{RRM}	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 70\text{ A}$ $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 15\text{ V}$ $T_j = 150\text{ }^\circ\text{C}$ (see test circuit, Figure 5)		70 105 2.4		ns nC A

(*) Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %.

(\bullet) Pulse width limited by safe operating area.

SCHOTTKY STATIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_R (*)$	Reversed Leakage Current	$T_j = 25\text{ }^\circ\text{C}$ $V_R = 30\text{ V}$ $T_j = 125\text{ }^\circ\text{C}$ $V_R = 30\text{ V}$		0.03	0.2 100	mA mA
$V_F (*)$	Forward Voltage Drop	$T_j = 25\text{ }^\circ\text{C}$ $I_F = 3\text{ A}$ $T_j = 125\text{ }^\circ\text{C}$ $I_F = 3\text{ A}$		0.38	0.51 0.46	V V

Fig. 1: Unclamped Inductive Load Test Circuit

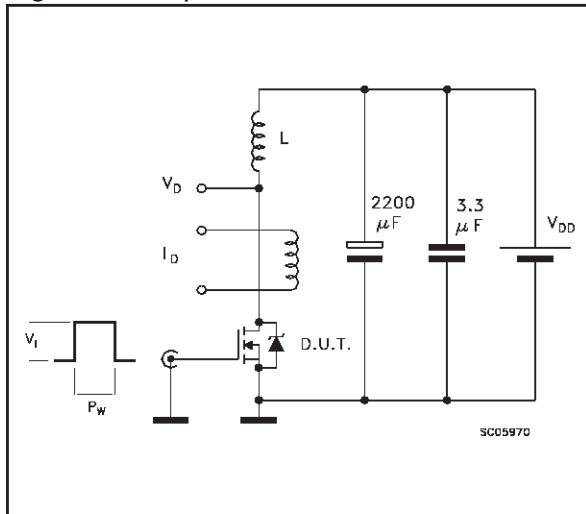


Fig. 2: Unclamped Inductive Waveform

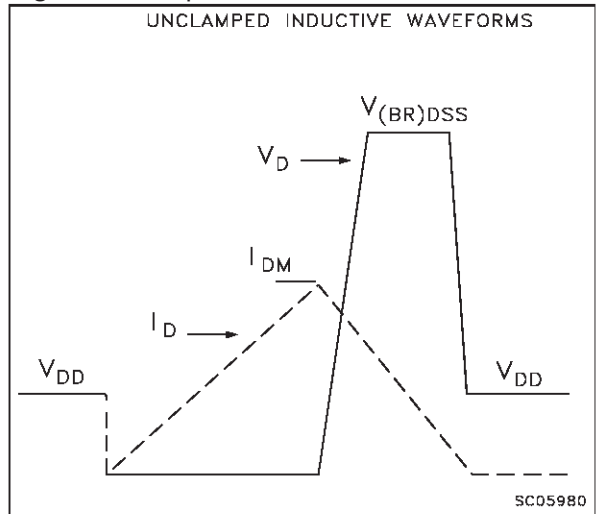


Fig. 3: Switching Times Test Circuits For Resistive Load

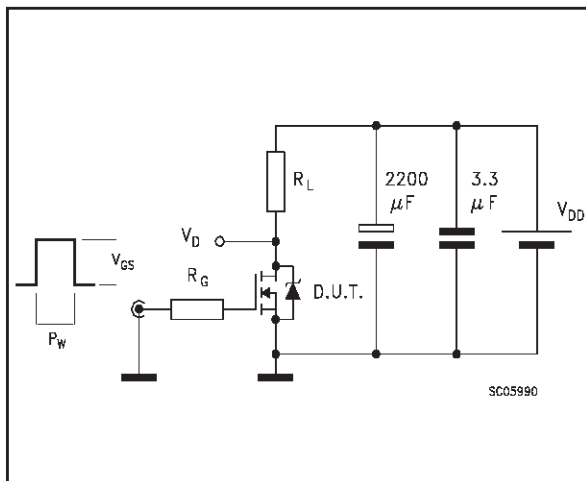


Fig. 4: Gate Charge test Circuit

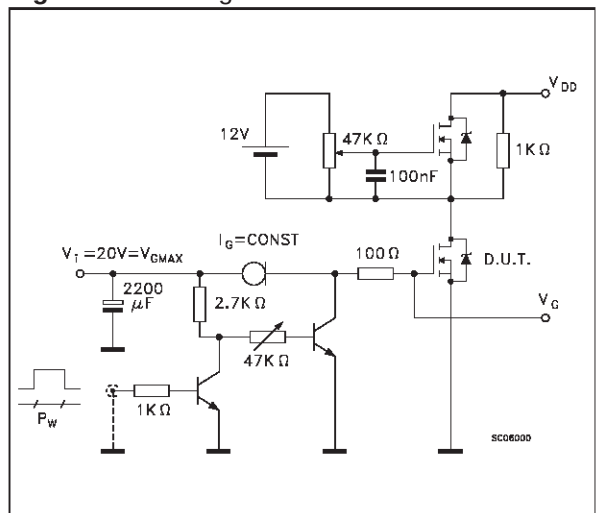
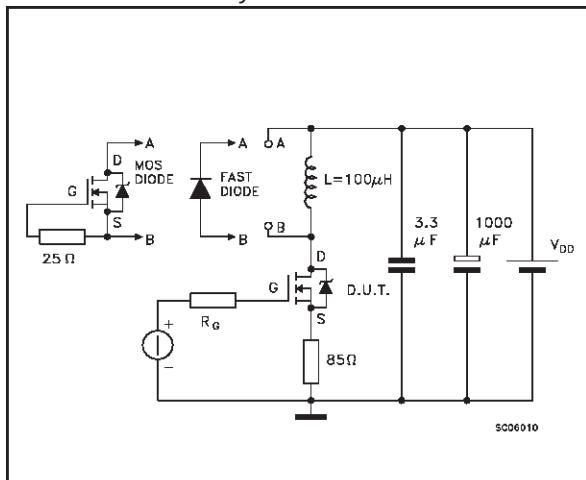
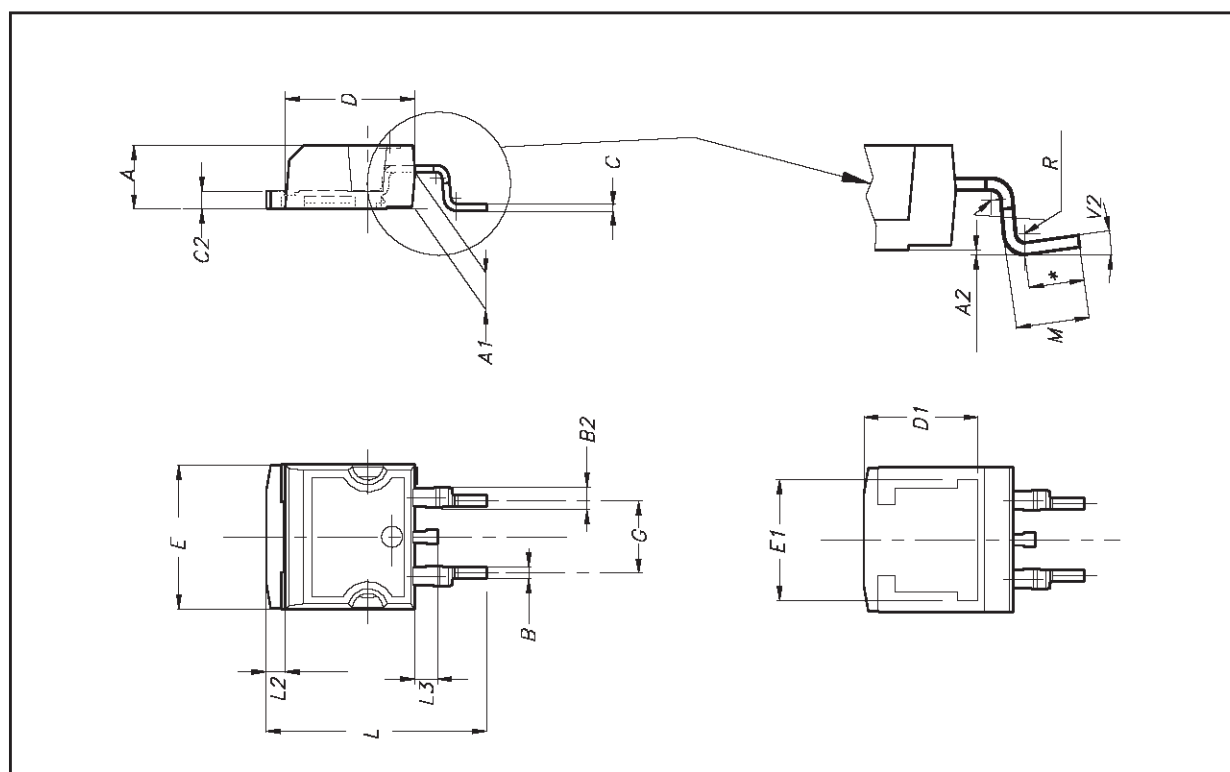


Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times



D²PAK MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
A1	2.49		2.69	0.098		0.106
A2	0.03		0.23	0.001		0.009
B	0.7		0.93	0.027		0.036
B2	1.14		1.7	0.044		0.067
C	0.45		0.6	0.017		0.023
C2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1		8			0.315	
E	10		10.4	0.393		
E1		8.5			0.334	
G	4.88		5.28	0.192		0.208
L	15		15.85	0.590		0.625
L2	1.27		1.4	0.050		0.055
L3	1.4		1.75	0.055		0.068
M	2.4		3.2	0.094		0.126
R		0.4			0.015	
V2	0°		8°			



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